

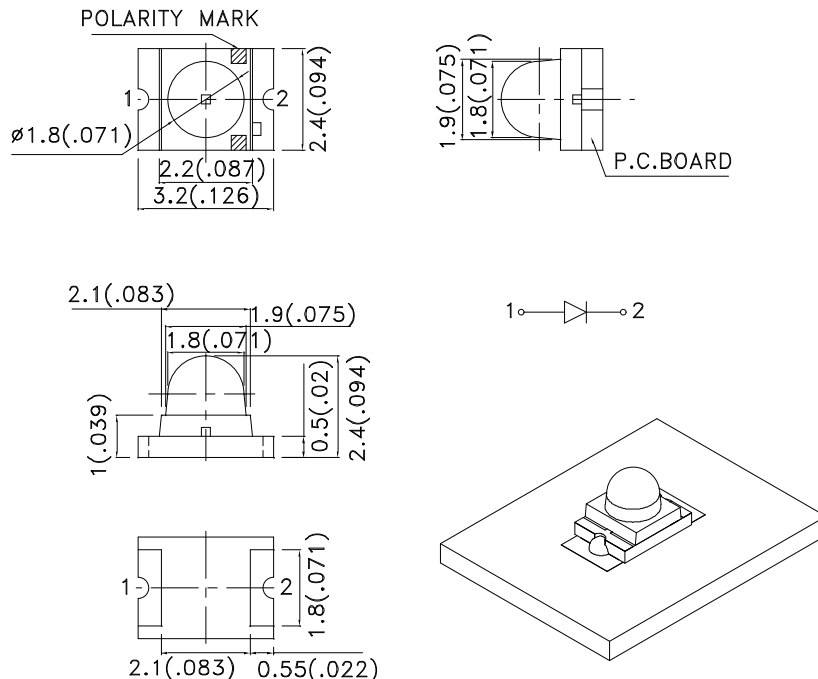
### Features

- 3.2x2.4mm SMT LED, 2.4mm THICKNESS.
- LOW POWER CONSUMPTION.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 1500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

### Description

The Super Bright Orange device is made with InGaAlP (on GaAs substrate) light emitting diode chip.

### Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.1(0.004)$  unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KPD-3224SEC	Super Bright Orange (InGaAlP)	WATER CLEAR	650	2000	20°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA
C	Capacitance	Super Bright Orange	30		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR=5V

Notes:

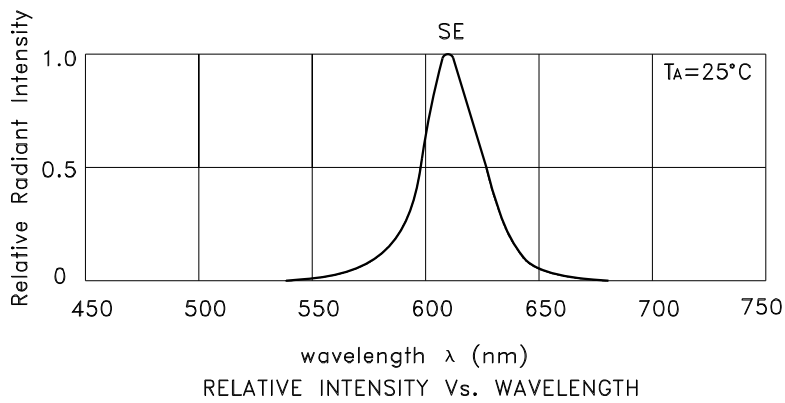
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

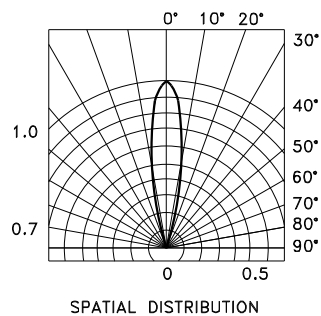
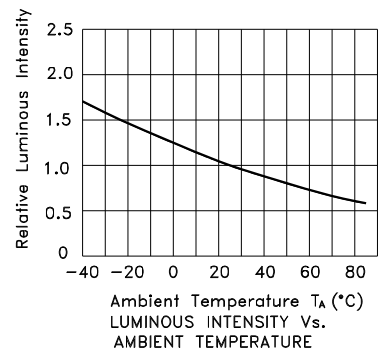
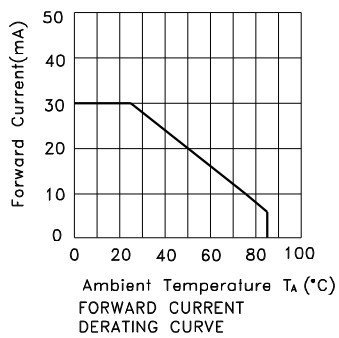
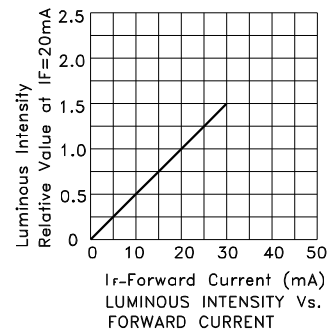
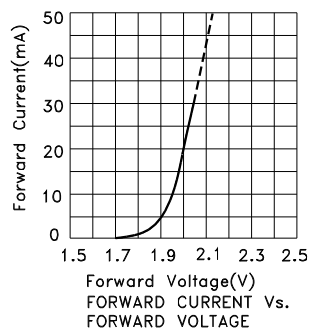
Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

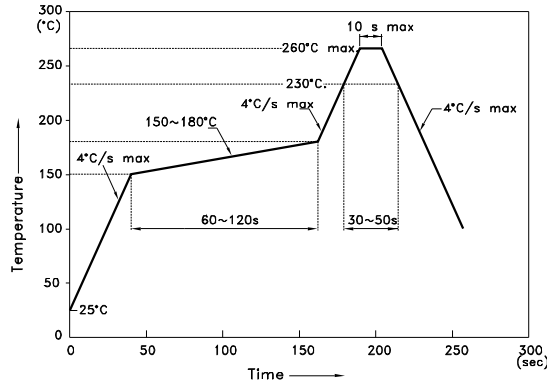


## Super Bright Orange KPD-3224SEC



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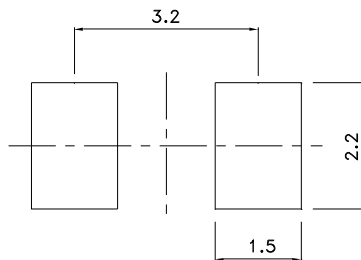
Reflow Soldering Profile For Lead-free SMT Process.



**NOTES:**

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

**Recommended Soldering Pattern  
(Units : mm; Tolerance: ± 0.1)**



**Tape Specifications  
(Units : mm)**

